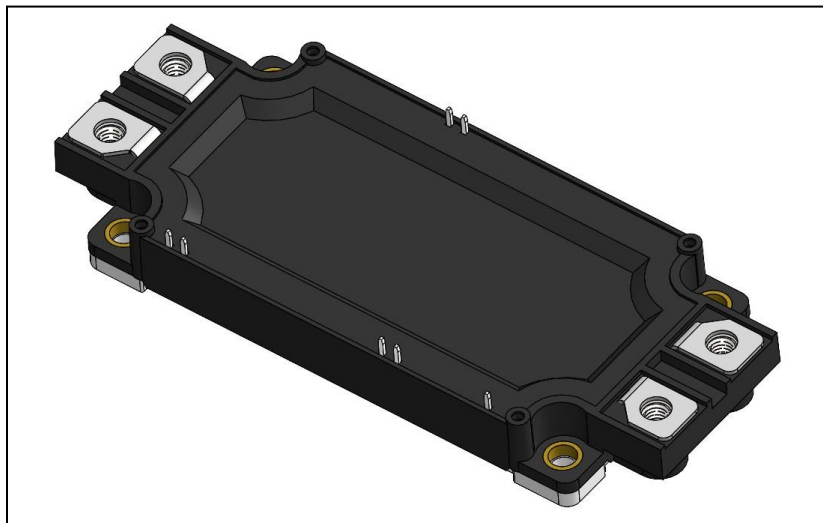
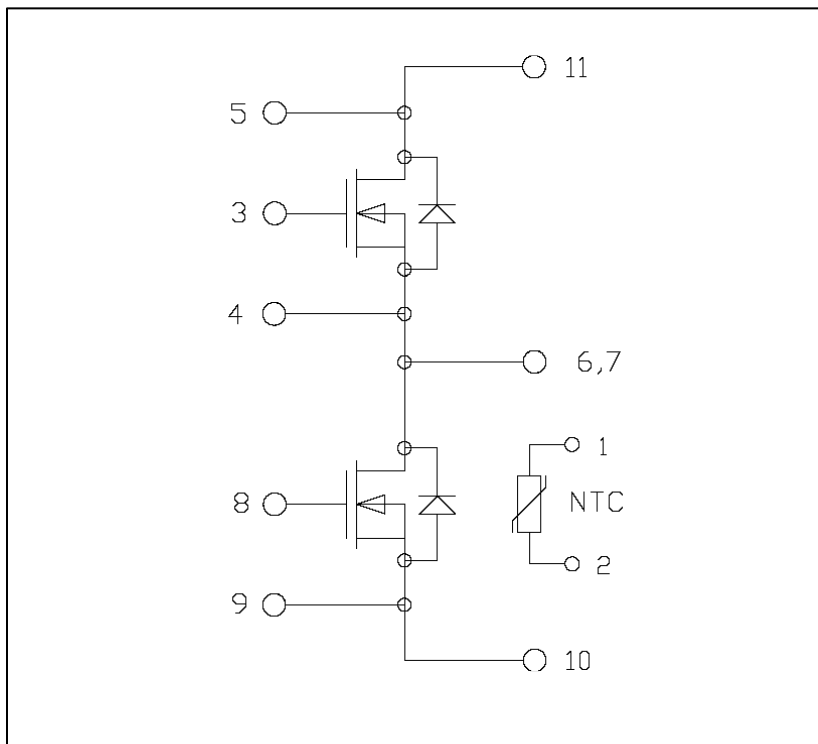


**Silicon Carbide
Dual MOSFET Module
400 Amperes / 1700 Volts / 3.6 mΩ**



**Dual SiC MOSFET Module
400 Amperes / 1700 Volts**



Description:

Powerex Silicon Carbide MOSFET Modules are designed for use in high frequency applications. Each module consists of two MOSFET Silicon Carbide Transistors with each transistor having a reverse connected super-fast recovery free-wheel silicon carbide Schottky diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

Features:

- ☐ Junction Temperature: 175°C
- ☐ Industry Leading $R_{DS(on)}$
- ☐ High Speed Switching
- ☐ Low Switching Losses
- ☐ Low Capacitance
- ☐ Low Drive Requirement
- ☐ High Power Density
- ☐ Zero Reverse Recovery from Diode
- ☐ Isolated Baseplate
- ☐ Aluminum Nitride Isolation

Applications:

- ☐ Energy Saving Power Systems
- ☐ High Frequency Type Power Systems
- ☐ High Temperature Power Systems

Absolute Maximum Ratings, $T_J = 25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	QJD1740SA1	Units
Drain-Source Voltage (G-S Short)	V_{DS}	1700	Volts
Gate-Source Voltage, DC, D-S short	V_{GS}	± 20	Volts
Drain Current (Continuous) at $T_C=48^\circ\text{C}^{*1}$	I_D	400	Amperes
Drain Current (Pulse, Repetitive) *2 , $T_{vj}=150^\circ\text{C}^{*3}$	$I_{D(pulse)}$	600	Amperes
Maximum Power Dissipation ($T_C=25^\circ\text{C}$, $T_J < 175^\circ\text{C}$) *1	P_D	1640	Watts
Maximum Junction Temperature	T_{Jmax}	175	$^\circ\text{C}$
Operating Junction Temperature, Continuous operation (under switching)	T_{jop}	-40 to 150	$^\circ\text{C}$
Maximum Case Temperature *1	T_{cmax}	125	$^\circ\text{C}$
Storage Temperature	T_{stg}	-40 to 125	$^\circ\text{C}$
Mounting Torque, M5 Mounting Screws	—	3.5	N-m
Terminal Connection Torque, M6 Terminal Screws	—	4.5	N-m
Module Weight (Typical)	—	420	Grams
Isolation Voltage	V_{ISO}	4000	Volts

*1 Case temperature (T_C) and heat sink temperature (T_s) are defined on the each surface (mounting side) of base plate and heat sink under the chips.*2 Pulse width and repetition rate should be such that device junction temperature (T_J) does not exceed $T_{J(MAX)}$ rating.*3 Junction temperature (T_{vj}) should not increase beyond $T_{J(MAX)}$ rating.**DC Characteristics, $T_J=25^\circ\text{C}$ unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain Source Leakage Current	I_{DSS}	$V_{DS}=1700\text{V}$, $V_{GS}=-15\text{V}$	-	-	1.0	mA
Gate Source Leakage Current	I_{GSS}	$V_{DS}=0\text{V}$, $V_{GS}=15\text{V}$	-	-	0.5	μA
Gate Source Threshold Voltage	$V_{GS(th)}$	$V_{DS}=10\text{V}$, $I_D=150\text{mA}$	1.8	-	3.2	Volts
Drain Source On-Resistance (chip)	$R_{DS(on)}$	$V_{GS}=15\text{V}$, $I_D=400\text{A}$	-	7.3	-	mΩ
		$T_J=150^\circ\text{C}$	-	10.74	-	mΩ
Internal Gate Source Series Resistance	R_g	Per Switch	-	0.375	-	Ω
Stray Inductance	L_s	P-N	-	15	-	nH

Dynamic Characteristics, $T_J=25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Input Capacitance	C_{ISS}	$V_{GS}=0V, V_{DS}=10V$	-	36.6	-	nF
Output Capacitance	C_{OSS}		-	22.6	-	nF
Reverse Transfer Capacitance	C_{RSS}		-	1.3	-	nF
Turn-On Delay Time	$t_{D(on)}$	$V_{DD}=900V, V_{GS}= \pm 15V$ $I_D=400A, R_G=1\Omega, T_J=150^\circ\text{C}$	-	200	-	ns
Rise Time	t_R		-	50	-	ns
Turn-Off Delay Time	$t_{D(off)}$		-	220	-	ns
Fall Time	t_F	Inductive Load, per Pulse	-	30	-	ns
Turn-On Energy	E_{on}	$V_{DD}=900V, V_{GS}= \pm 15V$	-	21.4	-	mJ
Turn-Off Energy	E_{off}	$I_D=400A, R_G=1\Omega, T_J=150^\circ\text{C}$ Inductive Load, per Pulse	-	6.6	-	mJ
Total Gate Charge	Q_G	$V_{DD}=900V, V_{GS}=0$ to 15V $I_D=400A, T_J=25^\circ\text{C}$	-	1066	-	nC

Anti-parallel Diode, $T_J=25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Diode Forward Voltage	V_{SD}	$V_{GS}=-15V, I_S=400A$	-	1.64	-	V
		$T_J=150^\circ\text{C}$	-	2.52	-	V

Thermal Resistance Characteristics

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	$R_{th(j-c)}$	Per MOSFET	-	-	0.091	$^\circ\text{C/W}$
Thermal Resistance, Junction to Case	$R_{th(j-c)}$	Per Diode	-	-	0.098	$^\circ\text{C/W}$
Contact Thermal Resistance	$R_{th(c-s)}$	Per Module, Thermal Grease Applied $\lambda=0.9 \text{ W/(mK)}$	-	0.015	-	$^\circ\text{C/W}$

NTC Thermistor Part

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Zero Power Resistance	R_{25}	$T_C=25^\circ\text{C}$	4.85	5.00	5.15	kΩ
Deviation of Resistance	$\Delta R/R$	$T_C=100^\circ\text{C}, R_{100}=493\Omega$	-7.3	-	+7.8	%
B constant	$B_{(25/50)}$	$B_{(25/50)}=\ln(R_{25}/R_{50}) / (1/T_{25} - 1/T_{50})^{*4}$	—	3375	—	K
Power Dissipation	P_{25}	$T_C=25^\circ\text{C}$	—	—	10	mW

*4 R_{25} : Resistance at Absolute Temperature T25 (K), R_{50} : Resistance at Absolute Temperature T50 (K), $T_{25} = 25(^\circ\text{C}) + 273.15 = 298.15(\text{K})$, $T_{50} = 50(^\circ\text{C}) + 273.15 = 323.15(\text{K})$

